WHAT IS CLAIMED IS:

1. An electronic component cleaning device for cleaning a site to be cleaned of an electronic component, comprising a plurality of spray units respectively adapted to spray a cleaning liquid to a plurality of spray-target regions between which the site to be cleaned is interposed, wherein

the plurality of spray-target regions are linearly extending,

the plurality of spray-target regions each has a spray pattern characterized in that a spray direction when viewed from a direction where the plurality of spray-target regions are linearly extending is perpendicular to a plane including the spray-target region,

the plurality of spray units are disposed such that the plurality of spray-target regions are arranged in juxtaposition each other, and

the cleaning liquid sprayed from the plurality of spray units crashes against the plurality of spray-target regions and thereby generates cleaning liquid flows headed for the site to cleaned,

wherein the site to be cleaned includes a clearance of the electronic component exposed toward the spray-target regions,

wherein the electronic component comprises a substrate or a wafer and an electronic circuit chip mounted on the substrate or the wafer, and wherein the clearance is formed between the substrate or the wafer and the electronic circuit chip.

2. The electronic component cleaning device as claimed in Claim 1, wherein the plurality of spray-target regions includes two spray-target regions between which the

site to be cleaned is interposed and the electronic component cleaning device further comprisesing a transport unit adapted to transport the electronic component from one of the two spray-target regions to the otheron two sides between which the site to be cleaned is interposed to the other spray-target region.

3. The electronic component cleaning device as claimed in Claim 2, wherein an interval distance betweenfrom one of the two spray-target regions on two sides between which the site to be cleaned is interposed to the other spray-target region is larger than a size of the site to be cleaned along a facing direction of the two spray-target regions on one of the two sides and the spray-target region on the other side.

4. The electronic component cleaning device as claimed in Claim 2, wherein the electronic component comprises a substrate or a wafer and an electronic chip mounted on the substrate or the wafer, wherein an interval distance D from one of the two spray-target regions to the otheron two sides between which the site to be cleaned is interposed to the other spray-target region and a width dimension L of the electronic component along a facing direction of the two spray-target regions on one of the two sides and the spray-target region on the other side fulfills a relationship expressed by the formula $L<D\leq (L+25\ mm)$.

5. The electronic component cleaning device as claimed in Claim 2, wherein the transport unit transports the electronic component at a transport rate from 100 to 1,500 mm/min.

6. The electronic component cleaning device as claimed in Claim 1, wherein a flow rate of the cleaning liquid flow sprayed from the spray units is from 0.03 m/sec. to 0.2 m/sec., and a spray pressure by the spray units is from 0.05 MPa to 0.8 MPa.

7. The electronic component cleaning device as claimed in Claim 1, wherein the spray unit includes a fan-type nozzle.

8. The electronic component cleaning device as claimed in Claim 7, wherein a cleaning liquid spray angle of the fan-type nozzle is at most 40°.

9. The electronic component cleaning device as claimed in Claim 1, wherein the spray unit includes a slit nozzle.

10. The electronic component cleaning device as claimed in Claim 2, wherein the spray unit each temporarily stops the spray of the cleaning liquid at times when the electronic component transported by the transport unit is passing through the spray-target regions.

11. An electronic component cleaning method for cleaning a site to be cleaned of an electronic component, wherein

an electronic component cleaning device is prepared, the device comprising a plurality of spray units respectively adapted to spray a cleaning liquid to a plurality of spray-target regions linearly extending, the plurality of spray units each having a spray pattern characterized in that a spray direction when viewed from a direction where the plurality of spray-target regions are linearly extending is perpendicular to a plane including the spray-target region, and the plurality of spray units being disposed such that the plurality of spray-target regions are arranged in juxtaposition each other,

the electronic component is situated such that the site to be cleaned is located at a position between the plurality of the spray-target regions, and

the cleaning liquid sprayed from the plurality of spray units crashes against the plurality of spray-target regions and thereby generates cleaning liquid flows headed for the site to cleaned to clean the site,

wherein the site to be cleaned includes a clearance of the electronic component exposed toward the spray-target regions,

wherein the electronic component comprises a substrate or a wafer and an electronic circuit chip mounted on the substrate or the wafer, and

wherein the clearance is formed between the substrate or the wafer and the electronic circuit chip.

12. The electronic component cleaning method as claimed in Claim 11, wherein the plurality of spray-target regions includes two spray-target regions between which the site to be cleaned is interposed and the electronic component cleaning method cleans the site to be cleaned using the cleaning liquid flows while transporting the electronic component from one of the two spray-target regions to the other~~on two sides between which the site to be cleaned is interposed to the other spray-target region~~.